

## DESCRIPTION

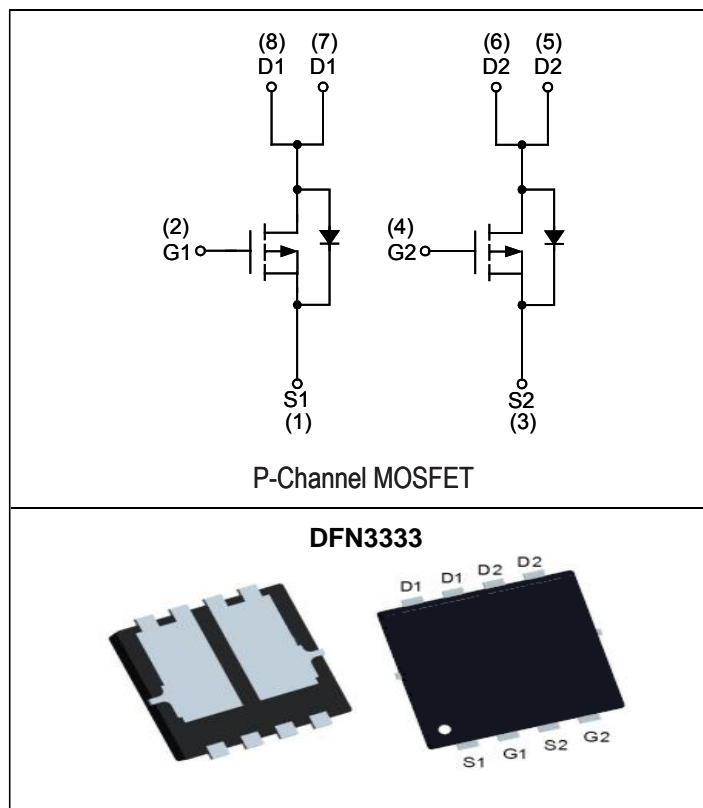
The 3429DE uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as a load switch or in PWM applications.

## GENERAL FEATURES

- $V_{DS}$  -20V
- $I_D$  -30A
- $R_{DS(ON)}$ ( at  $V_{GS}=-4.5V$ ) <19 mohm
- $R_{DS(ON)}$ ( at  $V_{GS}=-2.5V$ ) <26 mohm
- $R_{DS(ON)}$ ( at  $V_{GS}=-1.8V$ ) <45 mohm
- Trench Power LV MOSFET technology
- High density cell design for Low  $R_{DS(ON)}$
- High Speed switching

## Application

- PWM applications
- Load switch
- Power management



### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	-20	V
Gate-source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current	$I_D$	$T_C=25^\circ\text{C}$ @ Steady State	-30
		$T_C=100^\circ\text{C}$ @ Steady State	-19
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	-40	A
Total Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$ @ Steady State	32
		$T_C=100^\circ\text{C}$ @ Steady State	12.8
Single Pulse Avalanche Energy <sup>B</sup>	$E_{AS}$	31	mJ
Thermal Resistance Junction-to-Case <sup>C</sup>	$R_{\theta JC}$	3.9	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+155	$^\circ\text{C}$

**ELECTRICAL CHARACTERISTICS** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V, T_C=25^\circ\text{C}$			-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}= \pm 10V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}= V_{GS}, I_D=-250\mu A$	-0.4	-0.62	-1.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}= -4.5V, I_D=-15A$		15.5	19	m $\Omega$
		$V_{GS}= -2.5V, I_D=-8A$		21	26	
		$V_{GS}= -1.8V, I_D=-6A$		30	45	
Diode Forward Voltage	$V_{SD}$	$I_S=-30A, V_{GS}=0V$		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	$I_S$				-30	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V, f=1\text{MHz}$		2050		pF
Output Capacitance	$C_{oss}$			411		
Reverse Transfer Capacitance	$C_{rss}$			362		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=-10V, V_{DS}=-15V, I_D=-15A$		30		nC
Gate Source Charge	$Q_{gs}$			5.3		
Gate Drain Charge	$Q_{gd}$			7.6		
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-15V, I_D=-15A,$ $R_{GEN}=2.5\Omega$		14		ns
Turn-on Rise Time	$t_r$			20		
Turn-off Delay Time	$t_{D(off)}$			95		
Turn-off Fall Time	$t_f$			65		

- A. Repetitive Rating: Pulse width limited by maximum junction temperature.  
 B.  $T_J=25^\circ\text{C}, V_{DD}=-15V, V_G=-10V, L=0.1\text{mH}, R_g=25\Omega$   
 C. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

## ■ Typical Performance Characteristics

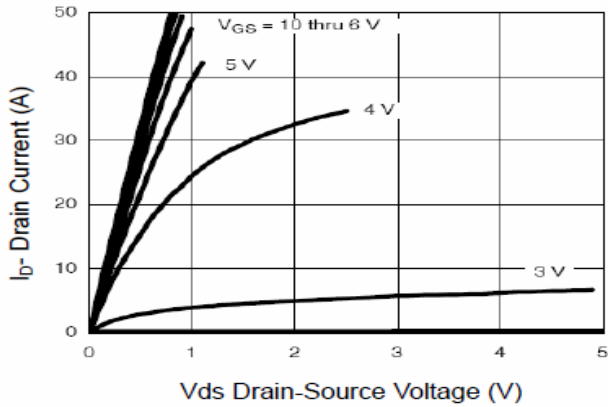


Figure1. Output Characteristics

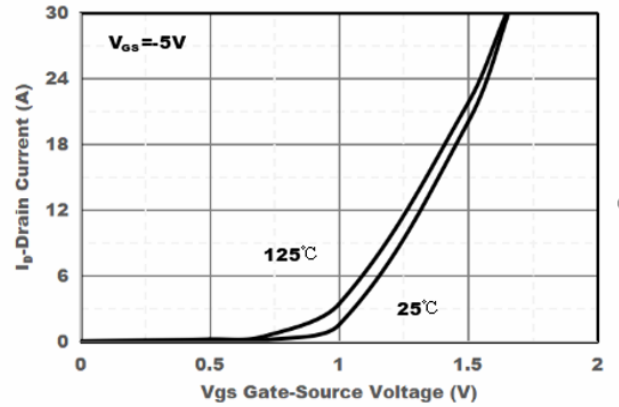


Figure2. Transfer Characteristics

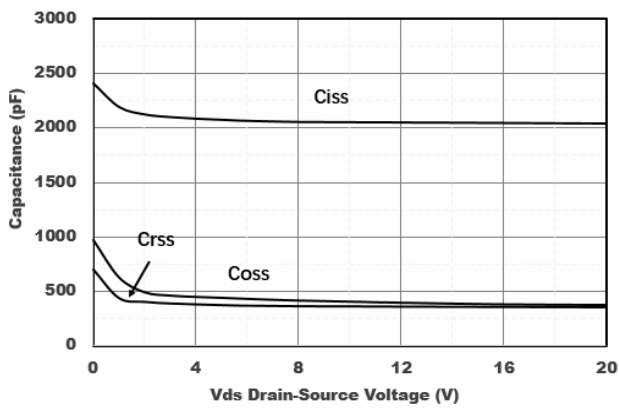


Figure3. Capacitance Characteristics

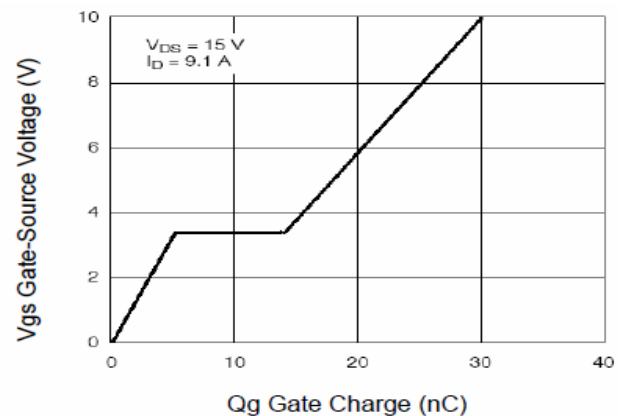


Figure4. Gate Charge

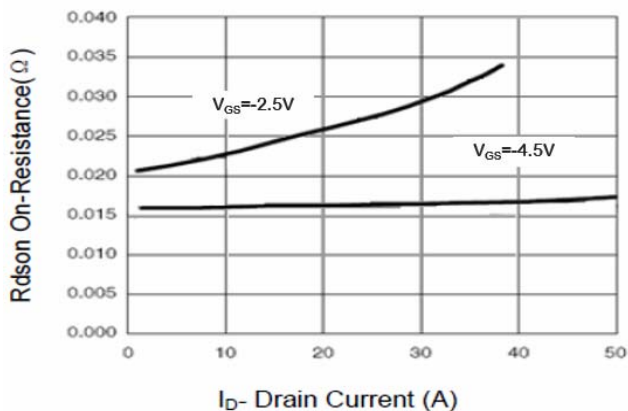


Figure5. Drain-Source on Resistance

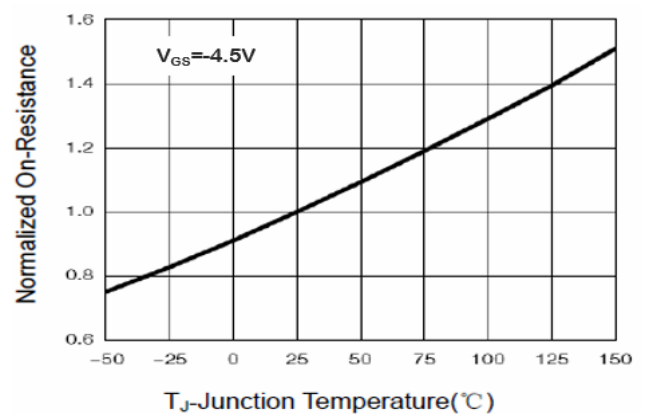


Figure6. Drain-Source on Resistance

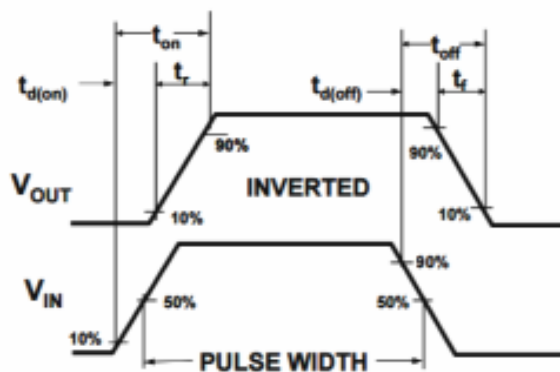
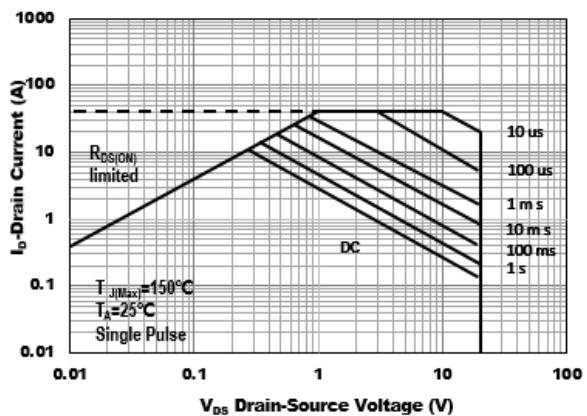
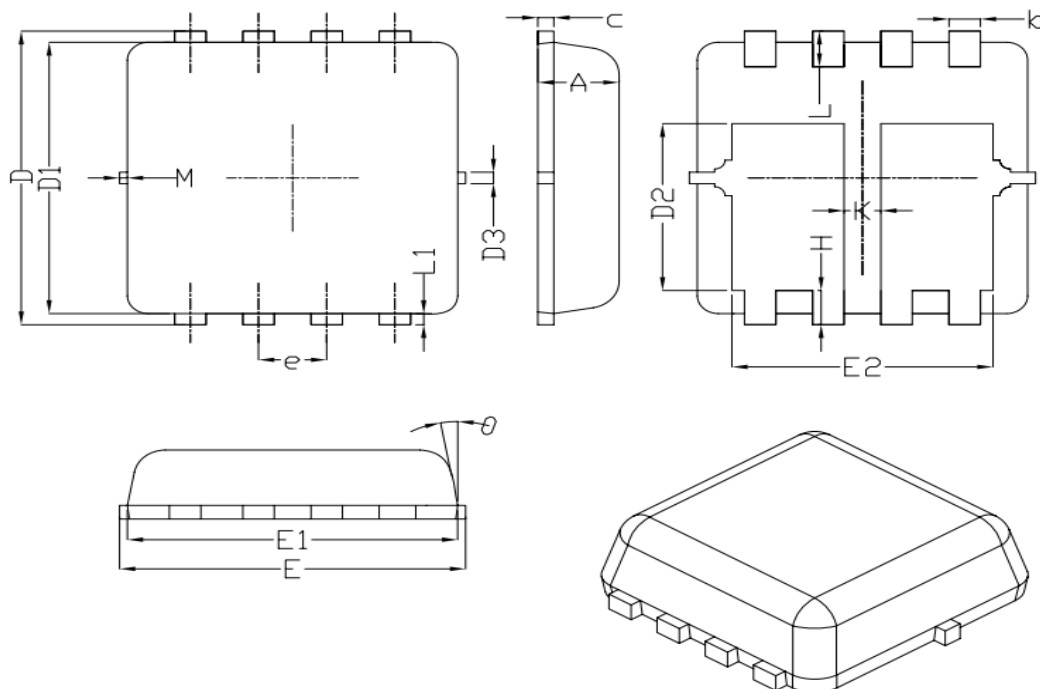


Figure8. Switching wave

## Package Information



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	--	0.13	--
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65 BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	--	0.13	--
K	0.30	--	--
$\theta$	--	10°	12°
M	*	*	0.15
* Not Specified			